



**NMPP e r
c o n P r**

UIM p p r o Q e d



Parameter		Symbol	Value	Unit
Input	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1 ⁷	\$
	5HYHUVH 9ROWDJH	9 ₅		
	3RZHU 'LVVLSDWLRQ	3 _·		
2XWSXW	6ZLWFKLQJ 9ROWDJH	2 _·	9	
	&RQWLQXRXV /RDG &XUHQW			
	3RZHU 'LVVLSDWLRQ	3&		P :
2SHUDWLQJ 7HPSHUDWXUH		7 _{RSU}	a	
-XQFWLRQ 7HPSHUDWXUH		7 _M		
6WRUDJH 7HPSHUDWXUH		7 _{VWJ}	a	
7RWDO 3RZHU 'LVVLSDWLRQ		3 _{WRW}		P :
,VRODWLRQ 9ROWDJH		9 _{LVR}	8	9UPV



Soldering Temperature	T_{sol}	260	
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NOTE1 1. The forward voltage V_F is measured at $I_F = 10mA$ and $T_J = 25^\circ C$.

NOTE2 2. The reverse current I_R is measured at $V_R = 6V$ and $T_J = 25^\circ C$.

ELECTRICAL CHARACTERISTICS (Temperature = 25 °C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F = 10mA$	-	1.2	1.5	V
	Reverse Current	I_R	$V_R = 6V$	-	-	1	μA
	Terminal Capacitance	C_T	$V = 0, f = 1MHz$	-	70	-	pF
	Reset Current	$I_F (OFF)$	$I_O = 0 (MAX)$	0.1	-	-	mA
Output	Open-circuit leakage current	I_{Leak}	$V_O =$				

ORDERING INFORMATION

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Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

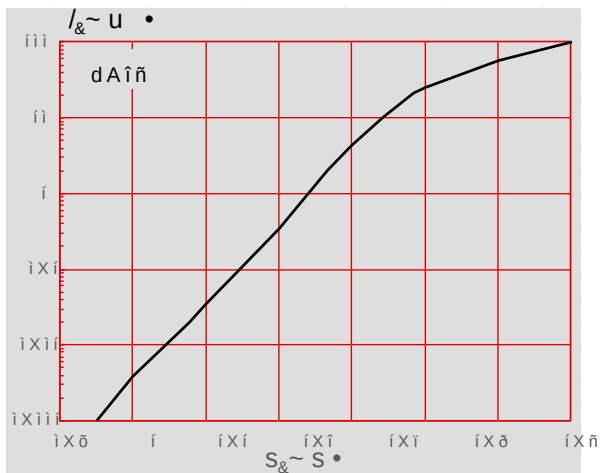


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

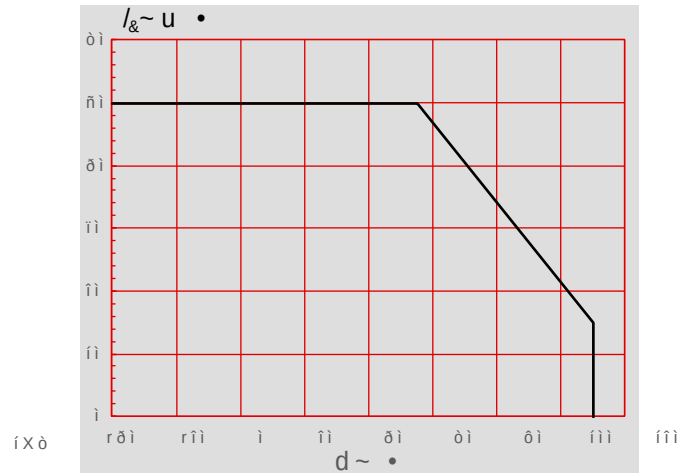


FIG.3: LED Operate Current vs. Ambient Temperature

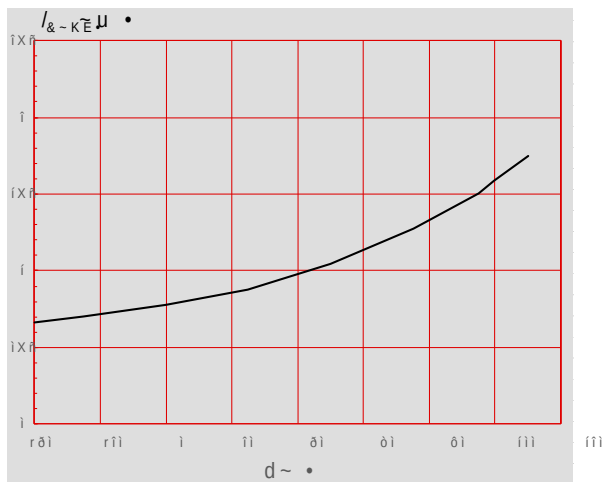


FIG.4: On Resistance vs. Ambient Temperature

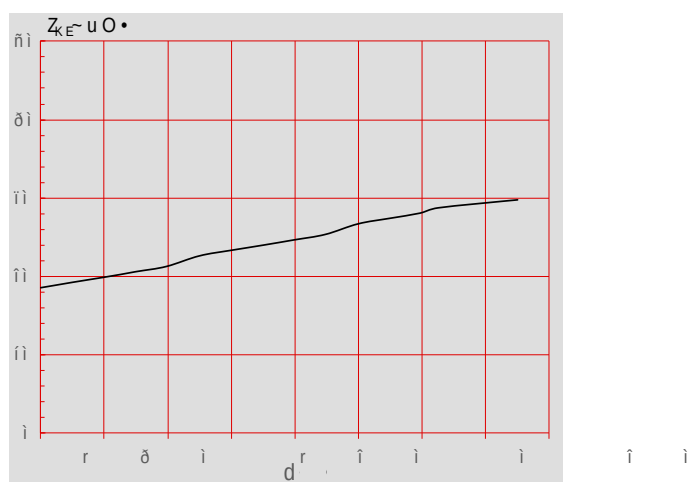


FIG.5: Turn On Time vs. Ambient Temperature

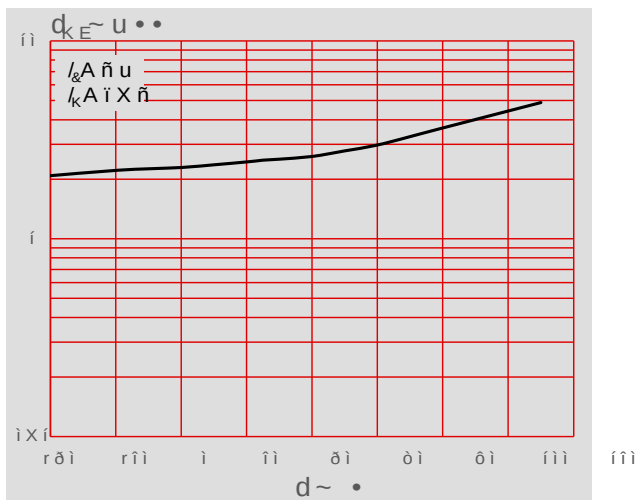
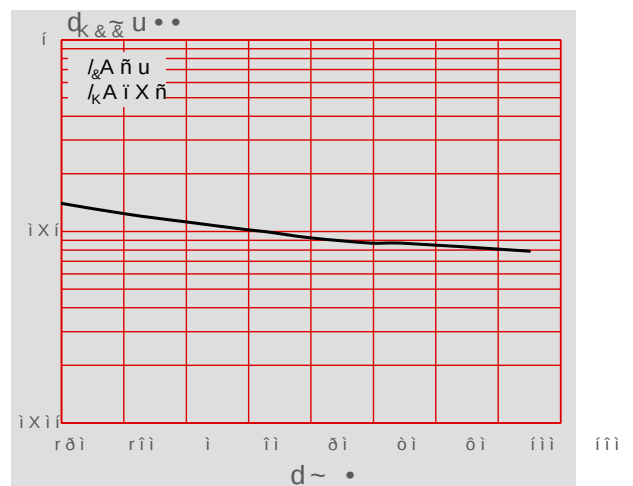
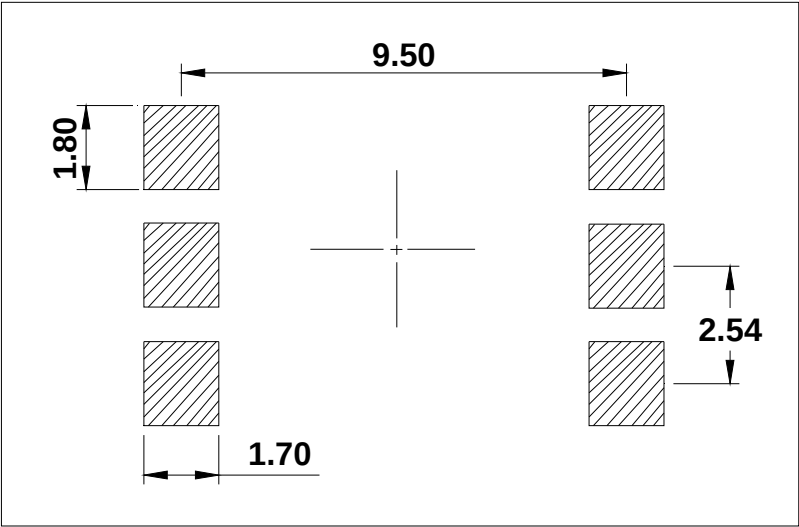


FIG.6: Turn Off Time vs. Ambient Temperature



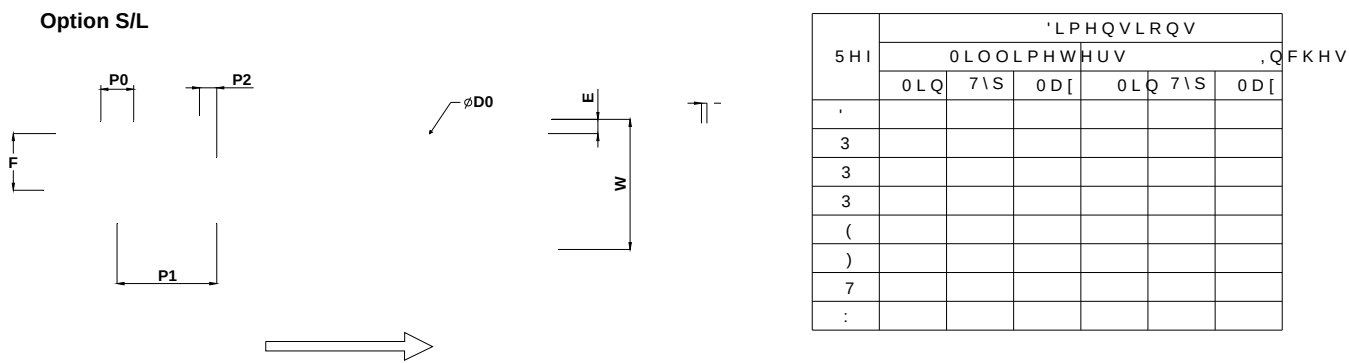
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SMD

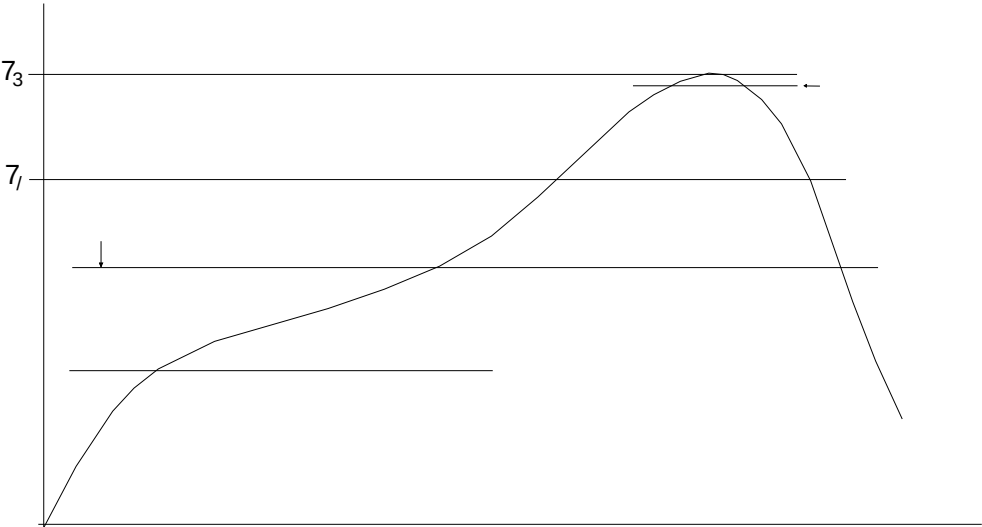
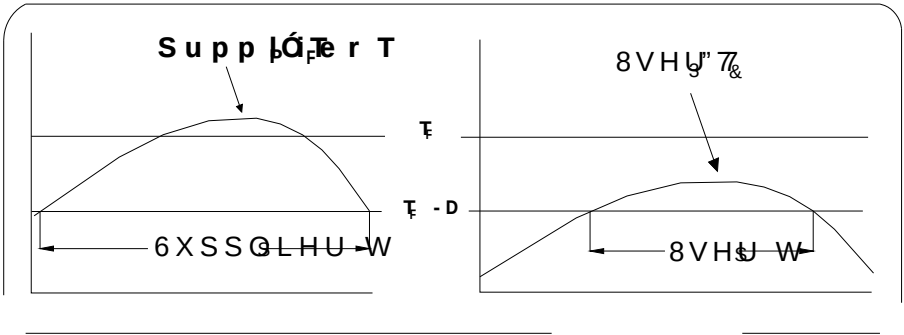


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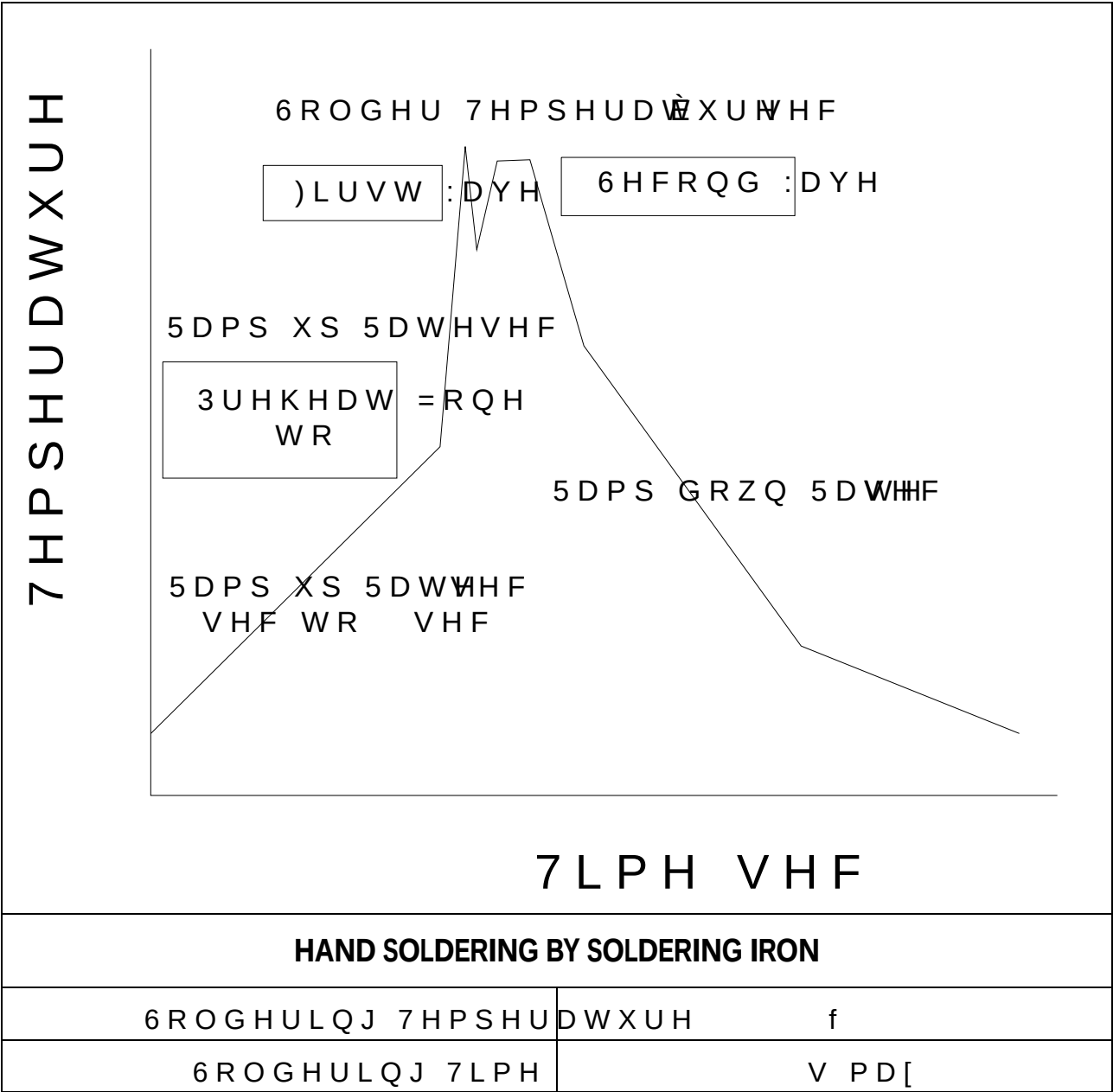
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



REFLOW INFORMATION



WAVE SOLDERING





Note:

1. Reflow soldering is recommended at the temperatures and time, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life